

Title (en)
SEMI-AROMATIC POLYAMIDE RESIN, METHOD FOR PREPARING SAME, AND POLYAMIDE MOLDING COMPOSITION CONSISTING OF SAME

Title (de)
HALBAROMATISCHES POLYAMIDHARZ, VERFAHREN ZUR HERSTELLUNG DAVON UND DARAUS BESTEHENDE POLYAMIDFORMMASSE

Title (fr)
RÉSINE POLYAMIDE SEMI-AROMATIQUE, SON PROCÉDÉ DE PRÉPARATION ET COMPOSITION DE MOULAGE DE POLYAMIDE LA COMPRENANT

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Abstract (en)
The present invention discloses a semiaromatic polyamide resin, a preparation method thereof, and a polyamide molding composition consisting of the same, which consists of following components: (A) 20 to 95 wt% of a PA10T homopolymer derived from 1,10-decanediamine and terephthalic acid; and (B) 5 to 80 wt% of a PA6T homopolymer derived from 1,6-hexanediamine and terephthalic acid. Particularly, (A) + (B) =100 wt%. In the present invention, by adding a certain amount of the PA10T homopolymer into the PA6T homopolymer, a melting point of the PA6T homopolymer can be significantly decreased to be below a decomposition temperature, and thereby a processability of the PA6T homopolymer is improved. The prepared semiaromatic polyamide resin has a decreased melting point, and may be processed normally. The polyamide molding composition consisting of the semiaromatic polyamide resin has a good processability, and has excellent surface properties.

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Cited by
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